MSU Electronics for LArIAT

Carl Bromberg Michigan State University

LArTPC electronics at MSU

Excellent Electronics Engineering at MSU – improving signal/noise at each stage below

Dan Edmunds

Bo – Warm amplifiers 3planes, 96 channels – tracks immediately (wire to disk) Bo – Warm amplifiers 3planes, 144 channels – new feedthru, bias C/R in LAr ArgoNeuT – Warm amplifiers, grid + 2 planes, 480 channels – bias C/R in LAr Bo – COLD CMOS Hybrid amplifiers 3planes, 144 channels, Warm Receiver/Driver Next step would be ASIC ...

Dan Edmunds & Dean Shooltz

LAPD – Reconfigured COLD CMOS (LongBo 2m drift) + 1 prototype 16 ch. BNL ASIC

<u>Dean Shooltz</u>

LArIAT (ArgoNeuT TPC) Not feasible to reuse ArgoNeuT electronics (but cables OK)

- FNAL Neutrino Dept. arranged BNL FE ASIC (50 uBoone spares) for us
- 10 Cold Mother Boards (CMB), 3 ASICs/CMB, circuit layout similar to uBoone
- New feedthru ASIC digital cont. + power + test pulse, ASIC analog out
- New Warm Receiver Driver card + Digital control + test pulse driver
- CAEN ADC single ended input D2S (differential to single ended) cards/crate
- Runs 1 & 2, now Run 3 in progress, all 480 ch. electronics operational

LArIAT Electronics

Cold Motherboard (48 ch)

PC board connectors to wire planes





Analog Out



May 16, 2017



Analog

Analog



Performance & Issues

<u>Run I</u>

Light System – coherent noise leaks – Shielding improved (got it <10% of stochastic noise) WRD – cable driver chip (uBoone) w/low-pass filter had MHz oscillations, remove C Grid Plane – Induction plane shadows. No Q-capacitor (ArgoNeuT missed it – Why? S/N !) PMTs – neg. HV on photocathode near collection plane wires, so major signal distortions ASIC serial data corruption – lowered impedance & reload each spill, acoustic wire motion

<u>Run II</u>

Most REPAIRED (or mitigated) by Run II

Beam Track Signal (~100 ADC counts = 50 mV) <u>Very Low</u> Noise (~1.4 counts = 0.7 mV) Convert noise to electrons:

> ASIC buffers off, we find 25mV/fC, 2us filter setting, yields 18 mV/fC ASIC output -> CAEN ADC input = 0.91 (18mV/fC) = <u>16.4 mV/fC @ CAEN</u> 0.7 mV: <u>ENC = 270 electrons (</u>reasonable for 0.5m wires +board capacitances)

Convert Beam track ionization to electrons: Basics (25 eV/ion, 2.2 MeV/cm, 1.4fC/mm) Drift field 500V/cm, tracks have 68% free ionization, 0.95fC/mm Expected Signal = 0.95fC/mm * 4.6mm = 4.4fC, without attenuation Beam tracks 50mV/16.4 mV/fC = 3fC (0.5 ms electron lifetime?)

<u>Run III</u> In progress – 5mm then 3mm pitch should see signal and noise.

Due to excellent S/N, we found a major problem with cold FE ASIC chip.

FE-ASIC - baseline restoration problem

What are these streaks? Same FE ASIC as uBoone did not see it initially, and 35-ton



BNL tracked this down and reports that increased transistor size in the ASIC polezero circuitry, has considerably reduced this baseline effect.

MSU enabling cold ASIC/FEMB testing (DUNE/SBN)

Cold Testing of 4 ASIC chips and/or full FEMBs

Avoid condensation at all costs (air carries dirt & contaminants). Seal and purge with GN2 Slow (but not too slow) cool down to 77K to avoid thermal shock Immerse in LN2 for full functionality testing Remove from LN2 and slow (but not too slow) warm up while purging with GN2

Dean Shooltz Implementation MSU providing 2 (perhaps 4) stations to BNL this month for such testing.

- 1) LN2 Dewar (below) filled once per day ~ 1 liter/cycle.
- 2) Electronics package lowered into slot and sealed in Cryostat
- 3) Purge cryostat with Dewar boil-off, with heaters & fans
- 4) Boil off valve closed, Dewar heated & LN2 rises into cryostat
- 5) Valve maintains LN2 below electronics while fans cool it
- 6) LN2 level raised to cover electronics cold testing now
- 7) Valve opens allowing LN2 to drain back to Dewar
- 8) Heaters and Fans raise temperature while GN2 purging

Cycle takes ~15 minutes. up to 16ASIC/hour/station up to 4 FEMB/hour/station



Want one?